

SID

Factory: Rot am See

Article:

ML8

Provided:

Customer:

Date:

24.04.2026



WÜRTH
ELEKTRONIK
MORE THAN
YOU EXPECT

Processtechnology: B: Pinlamination C: Pinlamination

Material Text	Mat. Nr.	µm	Stackup	Process overview
A-RS Kupferfolie-009my 330x490mm	50201012	9	VS	1
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	62		2
A-RS Kupferfolie-009my 330x490mm	50201012	33	L2	3
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	124		4
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	0		5
		35	L3	
C-RS-FR4-ML-0.107mm-035+035-TG150-HF-...	50203003	107		6
		35	L4	
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	120		7
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	0		8
		35	L5	
C-RS-FR4-ML-0.107mm-035+035-TG150-HF-...	50203003	107		9
		35	L6	
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	124		10
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	0		11
A-RS Kupferfolie-009my 330x490mm	50201012	33	L7	12
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	62		13
A-RS Kupferfolie-009my 330x490mm	50201012	9	RS	14

B00: C00

Thickness after Pressing

B00: 788 µm

Tol+: 79 µm

Tol-: 79 µm

Dmax: 867 µm

Dmin: 709 µm

C00: 860 µm

Tol+: 100 µm

Tol-: 100 µm

Dmax: 960 µm

Dmin: 760 µm

Thickness over all

0 µm

Tol+: 0 µm

Tol-: 0 µm

Dmax: 0 µm

Dmin: 0 µm

Demand for customer

Thickness (D): 1000 µm

Tol+: 100 µm

Tol-: 100 µm

Dmax: 1100 µm

Dmin: 900 µm

Measuring point: (05) over SM and galv. Cu; both sides

nominal: 930 µm

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